PCB Specification Document

Project Details

Specification name	GS-PCB-SPEC-0604
Release	1.0
Applicable projects	nanopower-bpx-2
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Release date	December 10, 2014

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Specifications

	Specification	Remarks
Base Specification	IPC-A-6012 cl. 3	
Construction	Multi-layer	
Material	Glass/polyimide (GI) IPC-4101/40 Arlon 85N	
Surface finish	Hot oil SnPb reflow	
Layer count	6	
Dimensions	78 mm x 40 mm	
Packaging	Individually in ESD bag. 10 pcs. in bigger bag	MIL-P-116G IA-8

Panelization

	Specification	Remarks
Delivery in panel	☑	
Panel dimensions		
Array count X x Y	2 x 2	

File List

Layer	File	File Extension
Stencil top	project-name	GTP
Notation top	project-name	GM5
Copper top	project-name	GTL
Inner 1	project-name	GP1
Inner 2	project-name	G1
Inner 3	project-name	G2
Inner 4	project-name	GP2
Copper bottom	project-name	GBL
Kapton mask bottom	project-name	GBS
Notation bottom	N/A	GM8
Stencil bottom	N/A	GBP
Board outline	project-name	GM4
Drill through	project-name	TXT
Drill blind top	N/A	TX1
Drill blind bottom	N/A	TX2
Panel drawing	project-name-panelization	PDF

Special processes

	Check	Remarks
Notation top	☑	White low-outgassing epoxy
Notation bottom	☐	White low-outgassing epoxy
Countersunk holes	☑	All 2.2mm holes from bottom. 90 degrees. Opening 4.5mm.
Copper filled vias (type VII)	☑	All vias
Hard gold contacts	☐	Filename
Electrical test	☑	
Impedance control	☐	Nets
Plasma etch-back	☑	
Plasma de-smearing	☑	
Manufacturer logo allowed	☐	No logo or production stamp allowed
Polyimide mask bottom	☑	Polyimide insulating mask laminated on bottom side. Free thickness < 70um

Build-up

	Thickness
Copper outer layers (incl. plating)	70 um
Copper inner layers	70 um
Thickness (over bare substrate)	1.5-1.7 mm